

### Normal Stress (1D)

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If the force acts normal to a surface, then the stress is called a **normal stress**

Force assumed uniform over the whole area A

Stress =  $\left\{ \begin{array}{l} \text{Force per} \\ \text{unit area} \end{array} \right\} = \sigma = \frac{F}{A}$  [N/m<sup>2</sup> = Pa]   
 standard mks unit

⇒ **Microscopic Definition**: force per unit area acting on the surface of a differential volume element of a solid body

⇒ **Note**: assume stress acts uniformly across the entire surface of the element, not at just a point

Differential volume element

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### Strain (1D)

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Sometimes a unit called the "microstrain" is used, where  $1 \mu\epsilon = \frac{\Delta L}{L}$  of 1 part in 10<sup>6</sup>

Strain =  $\left\{ \begin{array}{l} \text{Fractional Change} \\ \text{in length} \end{array} \right\} = \epsilon = \frac{L' - L}{L} = \frac{\Delta L}{L}$  [unitless]

In the elastic regime (i.e., for "small" stresses at "low" temperatures), strain is found to be proportional to stress

σ ← stress    For solids: MPa → GPa    σ = Eε →  $\epsilon = \frac{\sigma}{E}$  [unitless]

linear regime    slope = E = Young's modulus of elasticity    ε ← strain

Thus, the units of E are the same as σ → Pa

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### The Poisson Ratio

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Apply normal stress to a free-standing object } uniaxial strain  
but also get contraction in directions transverse to the uniaxial strain

⇒ contraction creates a (-) strain:

$$\epsilon_y = \frac{W' - W}{W} = \frac{\Delta W}{W} = -\nu \epsilon_x$$

ν = Poisson ratio [unitless]

↳ typical values: 0 → 0.5  
⇒ inorganic solids: 0.2 → 0.3  
⇒ elastomers (e.g., rubber): ~ 0.5

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### Shear Stress & Strain (1D)

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Note: Assume compensating forces are applied to the vertical faces to avoid a net torque. (This by convention.)

Shear Stress =  $\left\{ \begin{array}{l} \text{Force per Unit Area} \\ \text{Parallel to the Surfaces} \end{array} \right\} = \tau = \frac{F}{A}$  [Pa]

Generates a shear strain:

Shear Strain =  $\theta = \frac{\tau}{G}$     G ≙ shear modulus

$$G = \frac{E}{2(1 + \nu)}$$

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### 2D and 3D Considerations

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- Important assumption: the differential volume element is in static equilibrium  $\rightarrow$  no net forces or torques (i.e., rotational movements)
  - Every  $\sigma$  must have an equal  $\sigma$  in the opposite direction on the other side of the element
  - For no net torque, the shear forces on different faces must also be matched as follows:

Stresses acting on a differential volume element

$$\tau_{xy} = \tau_{yx} \quad \tau_{xz} = \tau_{zx} \quad \tau_{yz} = \tau_{zy}$$

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### 2D Strain

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- In general, motion consists of
  - rigid-body displacement (motion of the center of mass)
  - rigid-body rotation (rotation about the center of mass)
  - Deformation relative to displacement and rotation

Area element experiences both displacement and deformation

- Must work with displacement vectors
- Differential definition of axial strain:  $\epsilon_x = \frac{u_x(x + \Delta x) - u_x(x)}{\Delta x} = \frac{\partial u_x}{\partial x}$

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### 2D Shear Strain

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Rotate clockwise by  $\theta_1$

$\Rightarrow$  For shear strains, must remove any rigid body rotation that accompanies the deformation

$\hookrightarrow$  use a symmetric definition of shear strain:

$$\tau_{xy} = \theta_2 + \theta_1 \approx \left( \frac{\Delta u_x}{\Delta y} + \frac{\Delta u_y}{\Delta x} \right) = \left( \frac{\partial u_x}{\partial y} + \frac{\partial u_y}{\partial x} \right)$$

For small amplitude deformations.

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### Volume Change for a Uniaxial Stress

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Stresses acting on a differential volume element

Given an  $x$ -directed uniaxial stress,  $\sigma_x$ :

$$\Delta x \rightarrow \Delta x (1 + \epsilon_x)$$

$$\Delta y \rightarrow \Delta y (1 - \nu \epsilon_x)$$

$$\Delta z \rightarrow \Delta z (1 - \nu \epsilon_x)$$

The resulting change in volume  $\Delta V$

$$\Delta V = \Delta x \Delta y \Delta z (1 + \epsilon_x)(1 - \nu \epsilon_x)^2 - \Delta x \Delta y \Delta z = \Delta x \Delta y \Delta z [(1 + \epsilon_x)(1 - 2\nu \epsilon_x) - 1]$$

{Assume small strains}  $\Rightarrow \Delta V = \Delta x \Delta y \Delta z [(1 + \epsilon_x)(1 - 2\nu \epsilon_x) - 1]$

$[(1 + m)x]^n \approx 1 + nm x \Rightarrow \approx \Delta x \Delta y \Delta z [1 + \epsilon_x - 2\nu \epsilon_x - 2\nu \epsilon_x^2 - 1]$

$\Delta V \approx \Delta x \Delta y \Delta z (1 - 2\nu) \epsilon_x$

For  $\nu = 0.5$  (rubber)  $\rightarrow$  no  $\Delta V$ !  
 $\nu < 0.5 \rightarrow$  finite  $\Delta V$

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### Isotropic Elasticity in 3D

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- Isotropic = same in all directions
- The complete stress-strain relations for an isotropic elastic solid in 3D: (i.e., a generalized Hooke's Law)

$$\varepsilon_x = \frac{1}{E} [\sigma_x - \nu(\sigma_y + \sigma_z)] \quad \gamma_{xy} = \frac{1}{G} \tau_{xy}$$

$$\varepsilon_y = \frac{1}{E} [\sigma_y - \nu(\sigma_z + \sigma_x)] \quad \gamma_{yz} = \frac{1}{G} \tau_{yz}$$

$$\varepsilon_z = \frac{1}{E} [\sigma_z - \nu(\sigma_x + \sigma_y)] \quad \gamma_{zx} = \frac{1}{G} \tau_{zx}$$

Basically, add in off-axis strains from normal stresses in other directions

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### Important Case: Plane Stress

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- **Common case:** very thin film coating a thin, relatively rigid substrate (e.g., a silicon wafer)

- At regions more than 3 thicknesses from edges, the top surface is stress-free  $\rightarrow \sigma_z = 0$
- Get two components of in-plane stress:
 
$$\varepsilon_x = (1/E)[\sigma_x - \nu(\sigma_y + 0)]$$

$$\varepsilon_y = (1/E)[\sigma_y - \nu(\sigma_x + 0)]$$

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### Important Case: Plane Stress (cont.)

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- Symmetry in the xy-plane  $\rightarrow \sigma_x = \sigma_y = \sigma$
- Thus, the in-plane strain components are:  $\varepsilon_x = \varepsilon_y = \varepsilon$  where

$$\varepsilon_x = (1/E)[\sigma - \nu\sigma] = \frac{\sigma}{[E/(1-\nu)]} = \frac{\sigma}{E'}$$

and where

$$\text{Biaxial Modulus } \triangleq E' = \frac{E}{1-\nu}$$

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### Edge Region of a Tensile ( $\sigma > 0$ ) Film

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Net non-zero in-plane force (that we just analyzed)

At free edge, in-plane force must be zero

Film must be bent back, here

There's no Poisson contraction, so the film is slightly thicker, here

Discontinuity of stress at the attached corner  $\rightarrow$  stress concentration

Peel forces that can peel the film off the surface

Extra peel force

Shear stresses

$F \neq 0$      $F = 0$

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### Linear Thermal Expansion

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- As temperature increases, most solids expand in volume
- Definition:** linear thermal expansion coefficient

$$\left. \begin{array}{l} \text{Linear thermal} \\ \text{expansion coefficient} \end{array} \right\} \triangleq \alpha_T = \frac{d\epsilon_x}{dT} \quad [\text{Kelvin}^{-1}]$$

**Remarks:**

- $\alpha_T$  values tend to be in the  $10^{-6}$  to  $10^{-7}$  range
- Can capture the  $10^{-6}$  by using dimensions of  $\mu\text{strain/K}$ , where  $10^{-6} \text{ K}^{-1} = 1 \mu\text{strain/K}$
- In 3D, get volume thermal expansion coefficient  $\rightarrow \frac{\Delta V}{V} = 3\alpha_T \Delta T$
- For moderate temperature excursions,  $\alpha_T$  can be treated as a constant of the material, but in actuality, it is a function of temperature

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### $\alpha_T$ As a Function of Temperature

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[Madou, Fundamentals of Microfabrication, CRC Press, 1998]

- Cubic symmetry implies that  $\alpha$  is independent of direction

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### Thin-Film Thermal Stress

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- Assume film is deposited stress-free at a temperature  $T_d$ , then the whole thing is cooled to room temperature  $T_r$
- Substrate much thicker than thin film  $\rightarrow$  substrate dictates the amount of contraction for both it and the thin film

Thermal strain of the substrate: (in one in-plane dimension)  
 $\epsilon_s = -\alpha_{T_s} \Delta T$ , where  $\Delta T = T_d - T_r$

If the film were not attached to the substrate:  $\epsilon_{f, \text{free}} = -\alpha_{T_f} \Delta T$   $\rightarrow$  over

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### Linear Thermal Expansion

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But the film is attached to the substrate, so the actual strain in the film is the same as that in the substrate:

$$\epsilon_{f, \text{attached}} = -\alpha_{T_s} \Delta T$$

Thus:

$$\text{Thermal Mismatch Strain} = \epsilon_{f, \text{mismatch}} = (\alpha_{T_f} - \alpha_{T_s}) \Delta T$$

$\hookrightarrow$  Note that this is biaxial strain  
 $\hookrightarrow$  it can only be developed by an in-plane biaxial stress:

$$\sigma_{f, \text{mismatch}} = \left( \frac{E}{1-\nu} \right) \epsilon_{f, \text{mismatch}}$$

Ex. Thin-film is polyimide  $\rightarrow \alpha_{T_f} = 70 \times 10^{-6} \text{ K}^{-1}$ ,  $E = 4.6 \text{ Pa}$   
 deposited @  $250^\circ\text{C}$ , then cooled to RT =  $25^\circ\text{C} \rightarrow \Delta T = 225 \text{ K}$     e.g.,  $\text{SiO}_2$

$$\epsilon_{f, \text{mismatch}} = (70 - 2.8) \mu (225) = 1.5 \times 10^{-2}$$

$$\sigma_{f, \text{mismatch}} = (46) (1.5 \times 10^{-2}) = 60.5 \text{ MPa}$$

$\leftarrow$  stress is (+),  $\therefore$  tensile  
 [-] would be compressive]

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## MEMS Material Properties

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## Material Properties for MEMS

Material	Density, $\rho$ , Kg/m <sup>3</sup>	Modulus, E, GPa	$E/\rho$ GN/kg-m
Silicon	2330	165	72
Silicon Oxide	2200	73	36
Silicon Nitride	3300	304	92
Nickel	8900	207	23
Aluminum	2710	69	25
Aluminum Oxide	3970	393	99
Silicon Carbide	3300	430	130
Diamond	3510	1035	295

Units: (m/s)<sup>2</sup>  
 $\downarrow$   
 $\sqrt{E/\rho}$  is acoustic velocity  
 $\downarrow$   
 units of m/s

[Mark Spearing, MIT]

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